

Specification Sheet

Customer Name	XXXX	CUST P/N	NA
Approval No.	PD	Temwell P/N	STSF-2437B69-S1109W
Lot No.		Date	2025.06.13
Description	SAW Filter (BandPass)	Version	A1

(1) Size Diagram (Unit : MM)

Top View

Side View

Bottom View

Pin Configuration

1	Input
4	Output
Others	Ground

(2) Electrical Specifications

Parameter	Item		Specification		
	MHz	Unit	Min.	Typical	Max.
Center Frequency	-	MHz	-	2437	-
Insertion Loss	2402.5-2421.5	dB	-	1.4	1.7
	2407.5-2426.5	dB	-	1.3	1.5
	2412.5-2461.5	dB	-	1.1	1.3
	2447.5-2466.5	dB	-	1.1	1.3
	2452.5-2471.5	dB	-	1.4	1.6
Inband Ripple	2402.5-2471.5	dB	-	1.0	2.0
VSWR	2402.5-2471.5	-	-	1.5	2.0
Attenuation	100-2320	dB	20	23	-
	2300-2370	dB	30	36	-
	2370-2390	dB	28	33	-
	2483.5-2500	dB	20	30	-
	2486-2497.5	dB	20	30	-
	2500-2520	dB	23	32	-
	2520-2570	dB	30	36	-
	2570-2620	dB	25	35	-
	2620-2690	dB	25	35	-
	4800-5000	dB	30	39	-
5205-5660	dB	30	36	-	
Operation Temperature	-20°C~+85°C	°C	-	-	-
Storage Temperature	-20°C~+85°C	°C	-	-	-
RF Power Dissipation	+29	dBm	-	-	-
DC Voltage	3	V	-	-	-

Remark: Note 1: Test Temperature: 25°C±2°C
 Note 2: Terminating source impedance: 50Ω. Terminating load impedance: 50Ω

(3) Test Circuit

Port	Matching Component
Input	L1 :22 nH (Ideal inductor)
Output	L2 :18 nH (Ideal inductor)

Figure 1 Electrical Characteristics: Passband

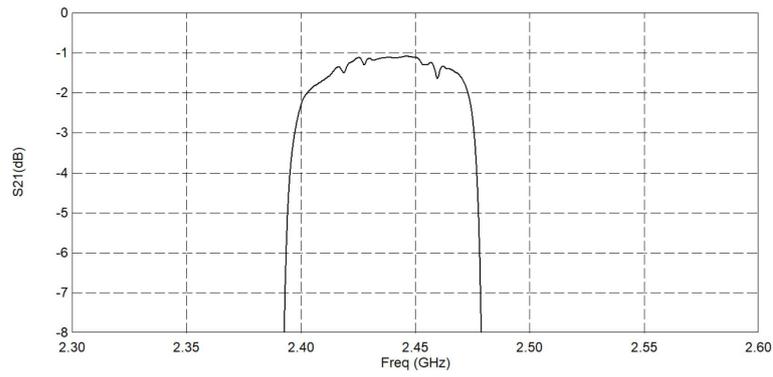


Figure 2 Electrical Characteristics: Narrowband

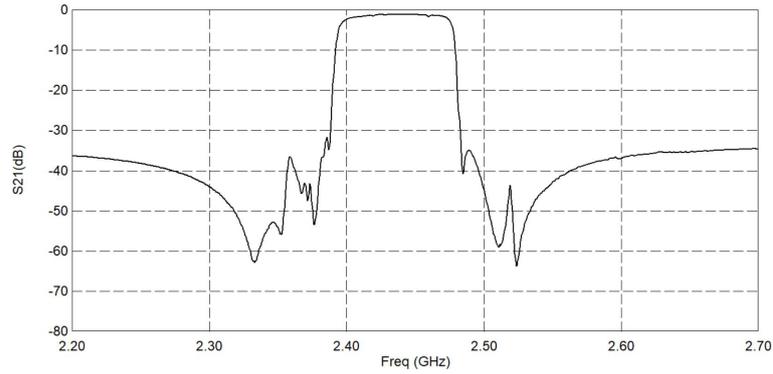


Figure 3 Electrical Characteristics: Wideband

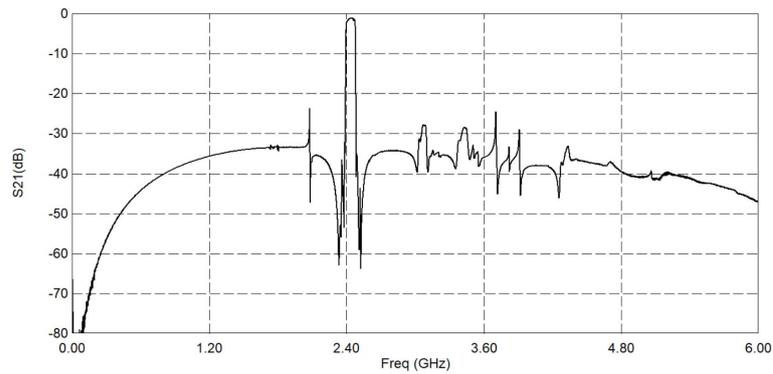
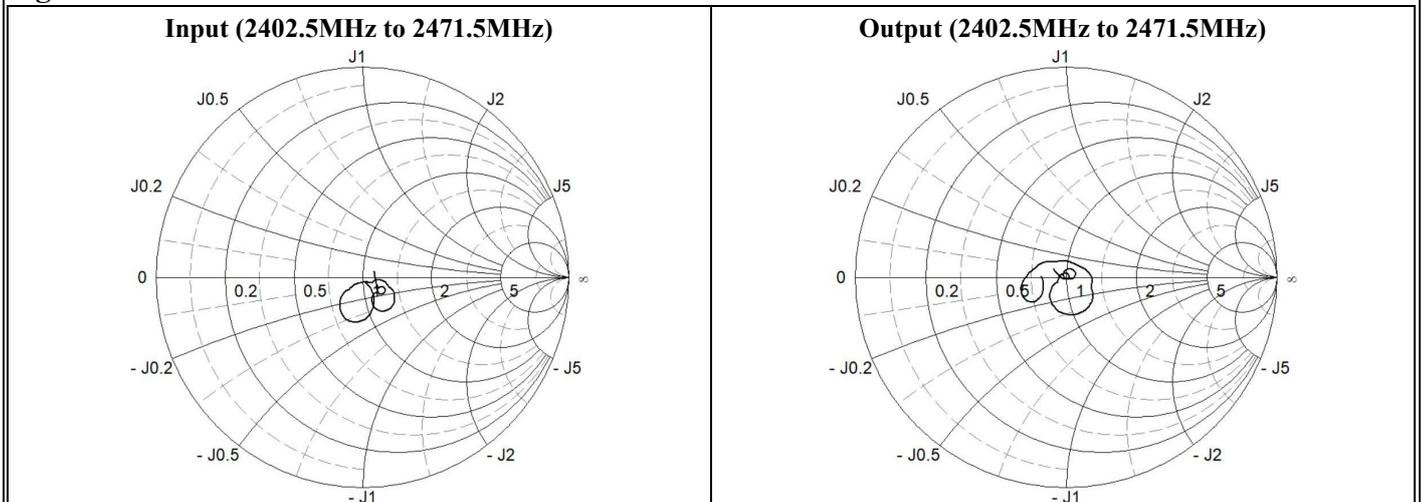
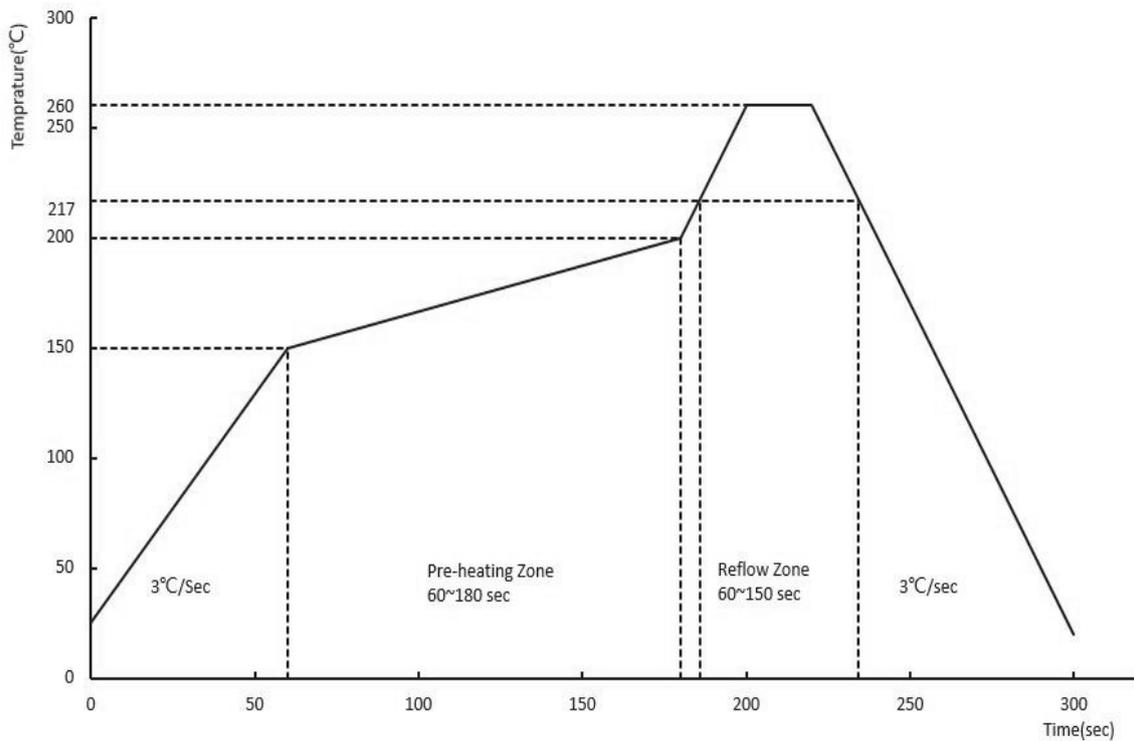


Figure 4 Smith Chart



Approval	Supervisor	Designer
C. K. Chang	M. Y. Chen	F.L.Lai

Recommended SMT Solder Profile



Reliability

No.	Test item	Test condition	
1	Temperature Storage	Temperature: 85°C±2°C , Duration: 250h , Recovery time: 2h±0.5h Temperature: -20°C±3°C , Duration: 250h ,Recovery time: 2h±0.5h	
2	Humidity Test	Conditions: 60°C±2°C ,90~95%RH	Duration:250h
3	Thermal Shock	Heat cycle conditions: TA=-20°C±3°C, TB=85°C±2°C, t1=t2=30min, Switch time: ≤3min, Cycle time: 100 times, Recovery time: 2h±0.5h.	
4	Vibration Fatigue	Frequency of vibration:10~55Hz Directions: X,Y and Z	Amplitude:1.5mm Duration: 2h
5	Drop Test	Cycle time:10times	Height:1.0m
6	Solder Ability Test	Temperature:245°C±5°C Depth: DIP--2/3, SMD--1/5	Duration:3.0s--5.0s
7	Resistance to Soldering Heat	Thickness of PCB:1mm , Solder condition: 260°C±5°C , Duration:10±1s Temperature of Soldering Iron: 350°C±10°C, Duration: 3~4s, Recovery time : 2 ± 0.5h	